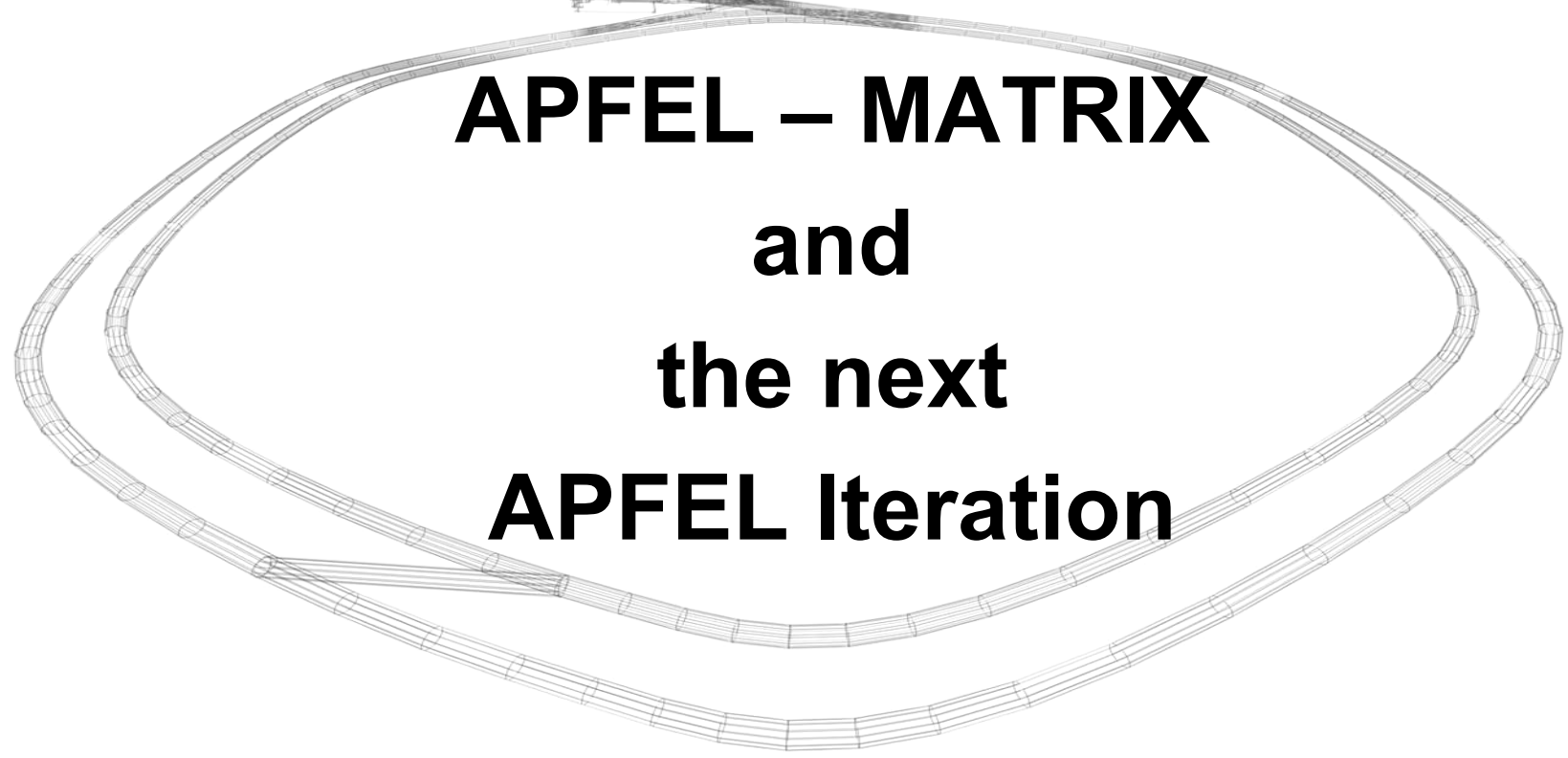


APFEL – MATRIX
and
the next
APFEL Iteration



Overview

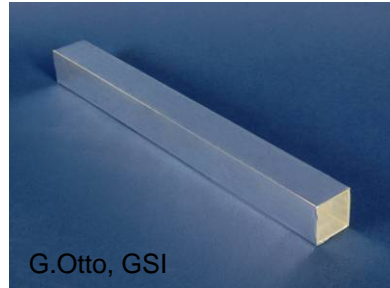
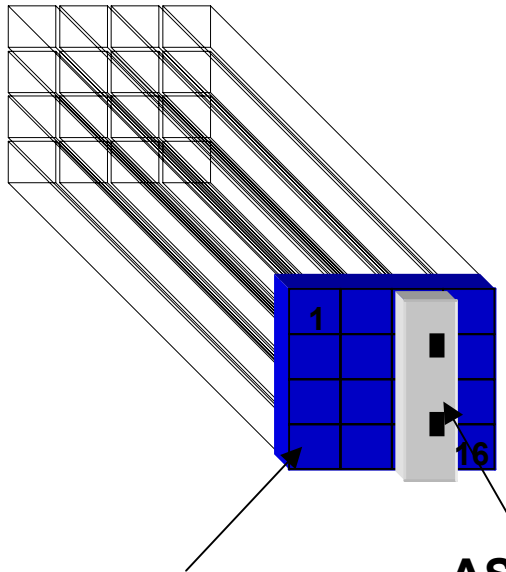
1. APFEL – MATRIX

- Setup of 16 crystals
- Readout system
- Data acquisition

2. Next APFEL Iteration

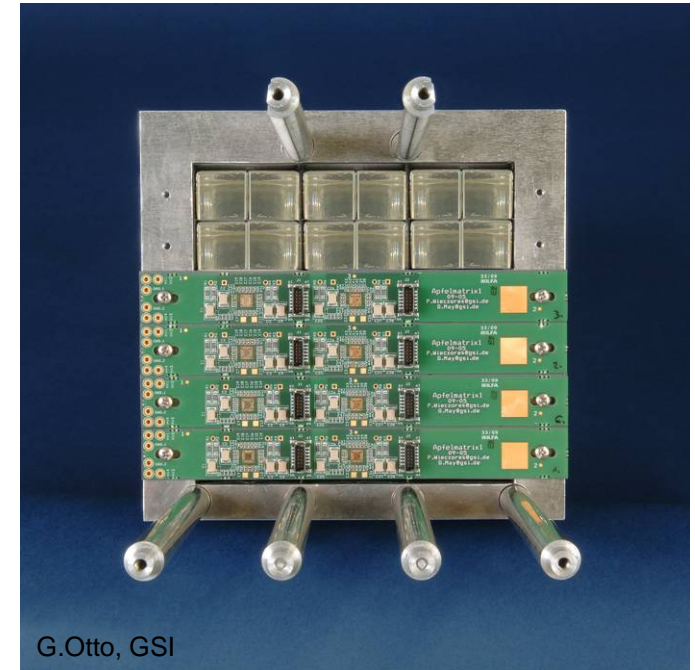
- APFEL design 2010
- Outlook

APFEL - MATRIX

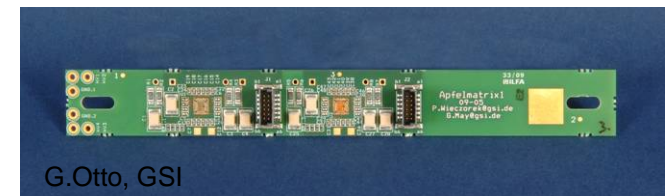


ASIC on a PCB

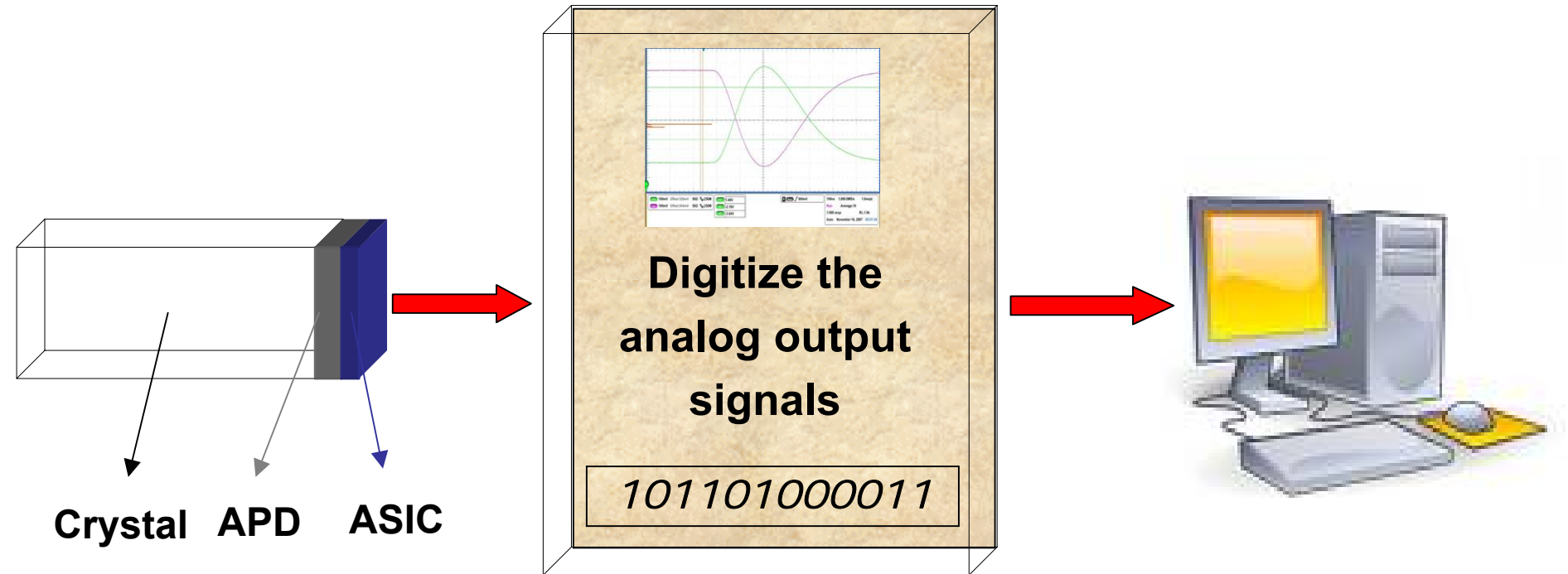
APD matrix



- Matrix readout
- 16 channels (one APD per crystal)
- Separate high voltages
- Two channel read out by one ASIC

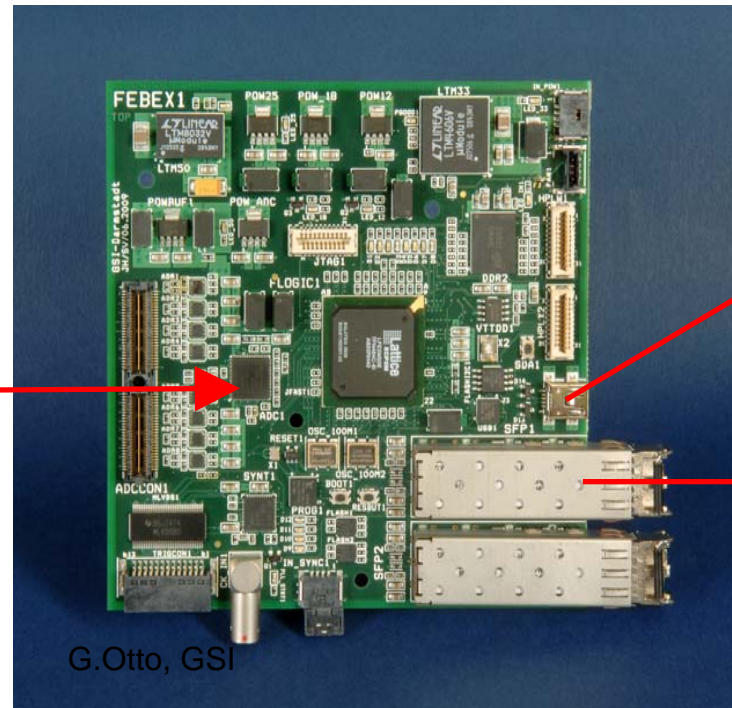
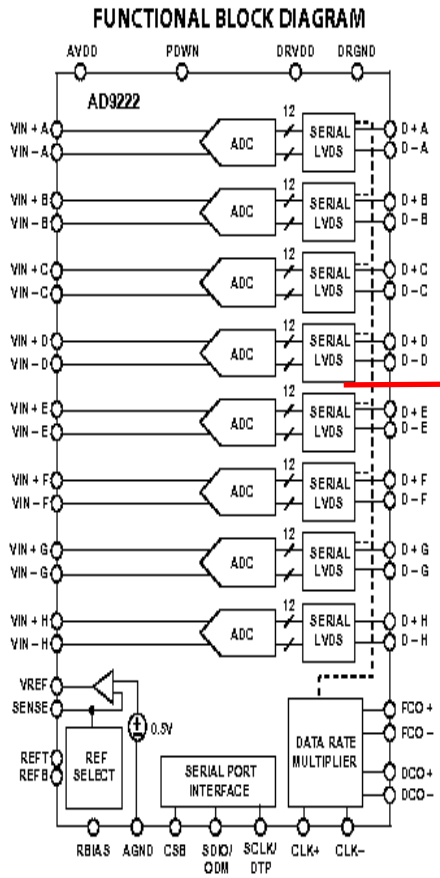


DAQ



- For the digitization
→ FEBEX – Board developed at GSI is used

FEBEX - Board Developed by J.Hoffmann

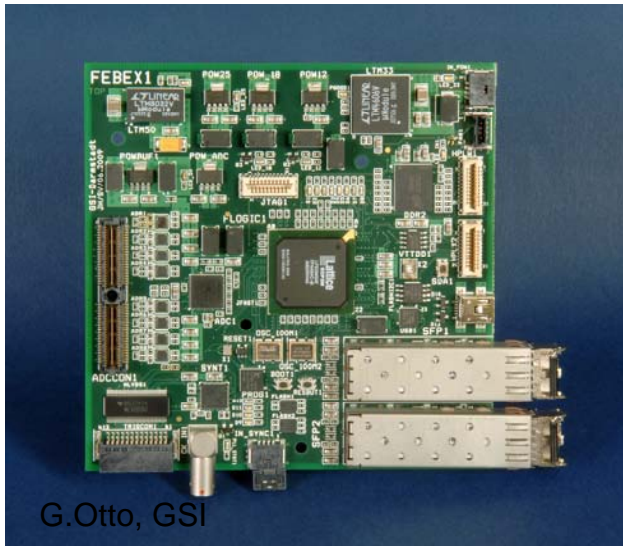


LAB:
USB - Interface

Optical Gbit
Interface to
DAQ

- 8 differential analog inputs
- ADC input range: ± 1 V
- ADC: 12 Bit, 65 MS/s
- 2 x 2.5 Gbit/s optical interface

FEBEX 2010



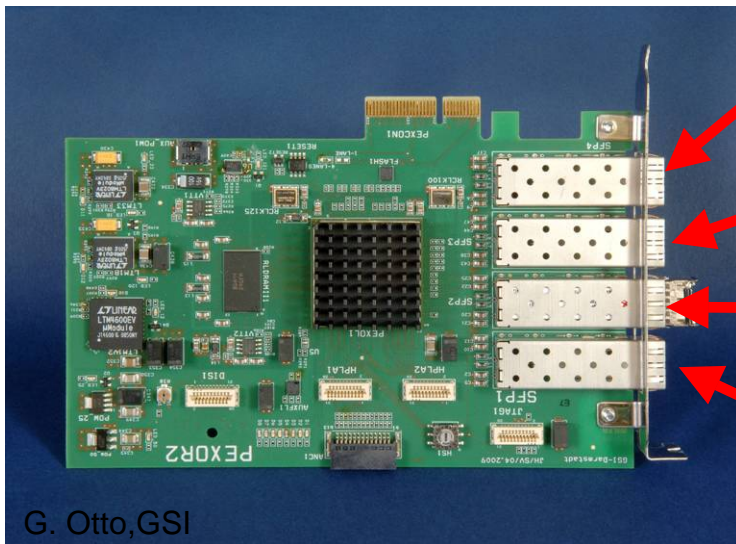
- Existing FEBEX – Board is a first prototype
 - Pulse shape analysis on the FPGA in development
 - 8 channels readout version
 - Internal FPGA memory buffer is large enough for 8 (30) μ s traces

- Next FEBEX - Board (design 2010)

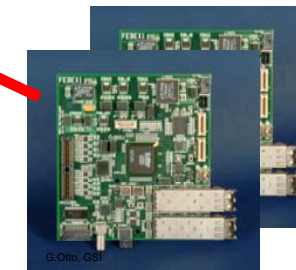
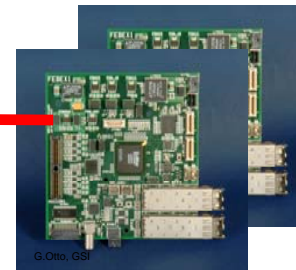
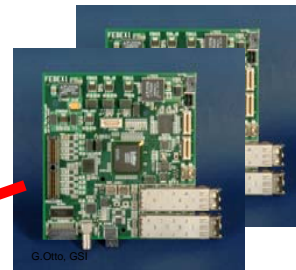
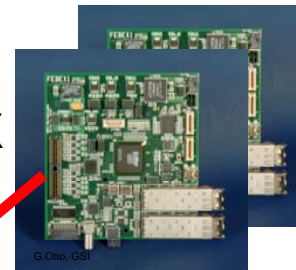
- Upgrade to 16 (32) channels
- More powerful FPGA
- Pulse shape analysis on the FPGA (will be done at KVI)
- Compatible ADCs (10, 12 or 14 Bit; 50 -100 MS/s)
- Larger memory (store more than 30 μ s time information)
- Prototype for a readout of 400 channels

PEXOR – FEBEX Connection

PEXOR – Board (PCIe)



FEBEX



4x up to
16 FEBEX
in series

- PEXOR – Board was designed by Jan Hoffmann
- Programming was done by Wolfgang Ott

DAQ Summary

To measure 16 differential outputs from the APFEL – Matrix existing DAQ components from GSI are used

- **Digitization and data transport: FEBEX – PEXOR – Board**
(contact: Jan Hoffmann)
- **DAQ – System: Multi Branch System (MBS)**
(contact: Wolfgang Ott, Nikolaus Kurz, <http://www.win.gsi.de/daq/>)
- **Online monitoring / offline analysis: GSI Object Oriented On-line Off-line system (GO4)**
(contact: Jörn Adamczewski-Musch, <http://www.win.gsi.de/go4/>)

Go4 MATRIX Display

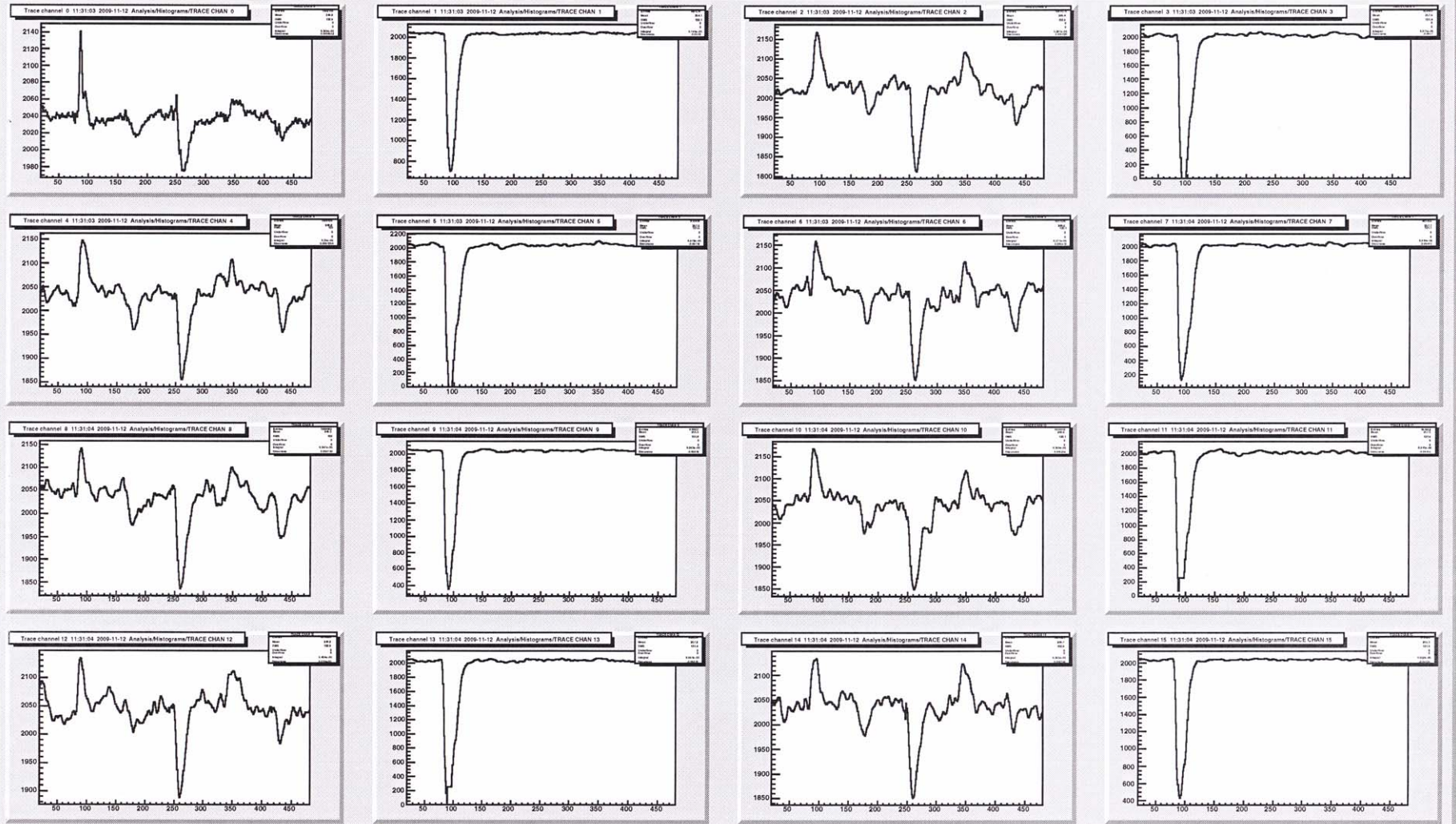
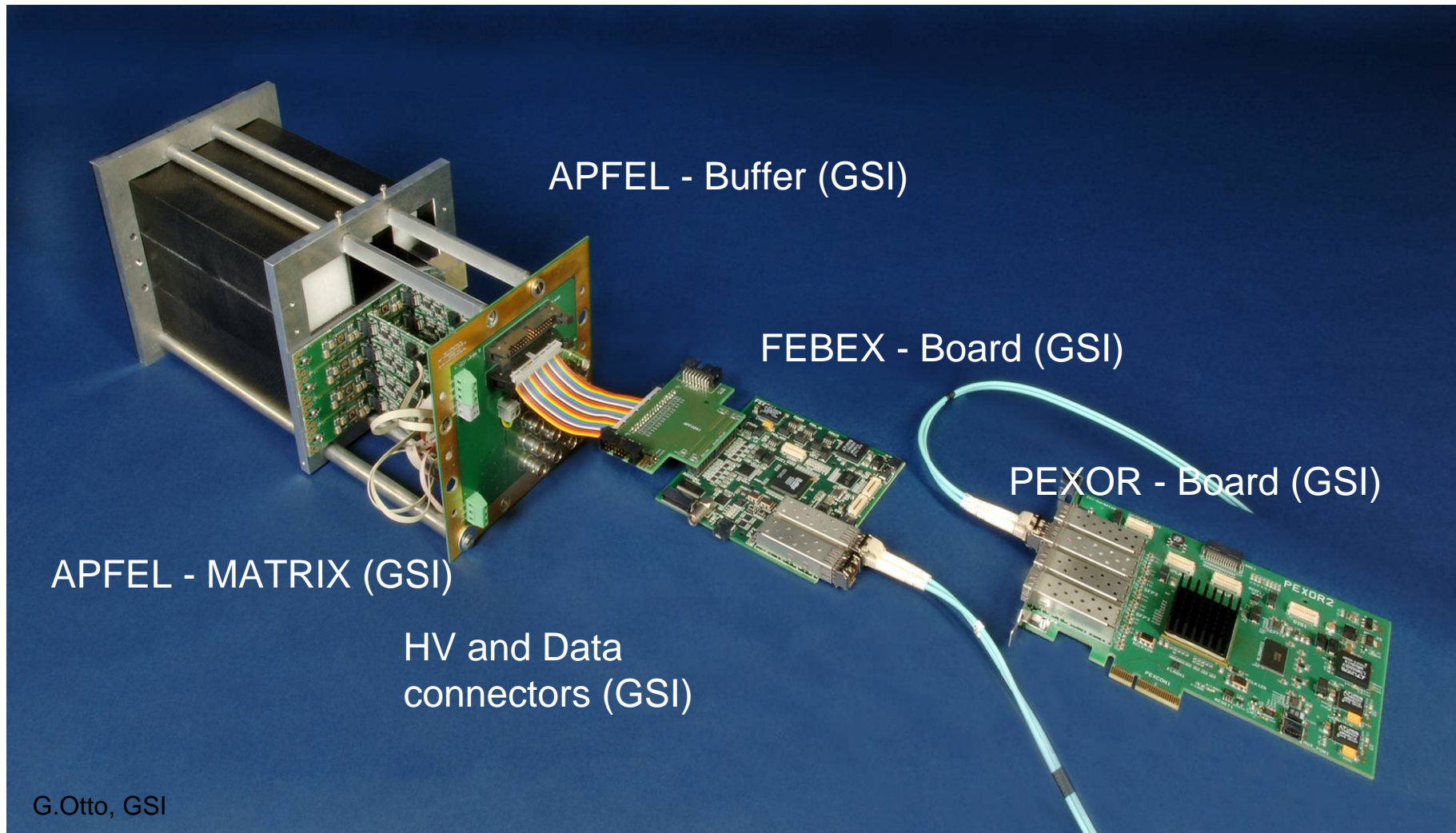


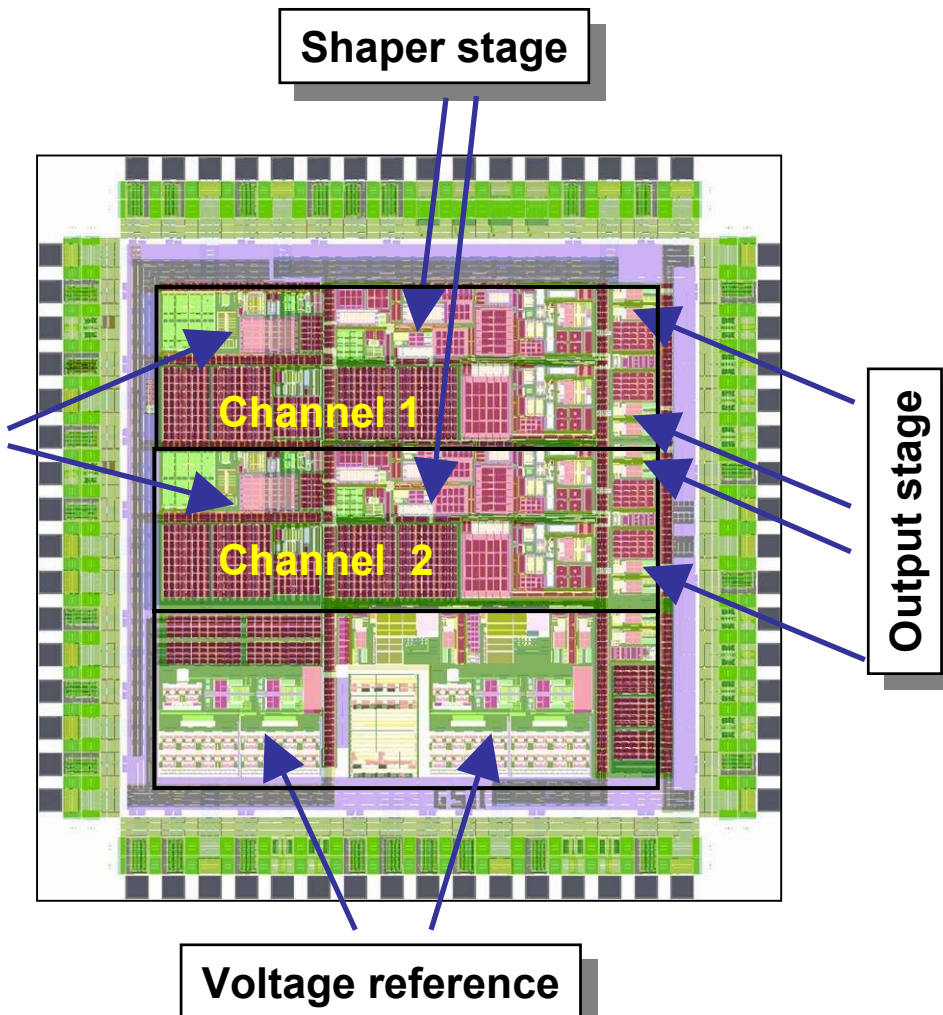
Photo of the APFEL - MATRIX Setup





Next Iteration of the APFEL - ASIC

Layout of the existing ASIC



- Process: 350 nm – CMOS (AMS)
- Two equivalent readout channels
- Programmable voltage references
- Dimension: 3.3 mm x 3.3 mm
- Pad connections: 64

Next Iteration

- **APFEL03: Manuel voltage reference programming with lookup tables for different temperatures is necessary**
 - **An autocalibration has been developed**
- **To operate the high and low amplification path of a channel in parallel an additional voltage reference DAC has been implemented**
- **For chip identification**
 - **Bugfix in chip – ID selection**
- **Open question: Output buffer ??? (final call !!)**
- **Status of the next APFEL – iteration:**
 - **Schematic review is done**
 - **Layout of the chip is in progress**

Outlook

- **First cosmic tests with the APFEL – MATRIX (Spring 2010)**
- **Submission of the next APFEL – ASIC iteration (Spring 2010)**
- **Commissioning of next APFEL iteration (Summer 2010)**
- **Do we need additional ASICs for further tests (more than 20)?**

